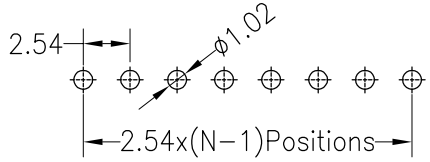
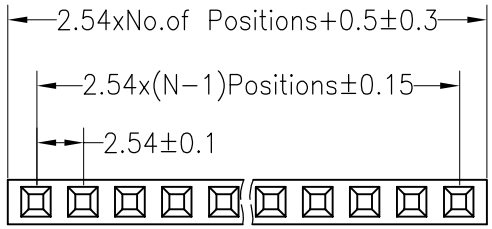
HSF RoHS

SPECIFICATIONS
Rated Current:3.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:1000V AC/DC
Insulation Resistance:1000MΩ Min
Operation Temperature:−40°c to +105°c

Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V−0)
Standard: PA6T
Max.Processing Temp: 230°C for 30−60 seconds
(260°C for 10 seconds)

Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)

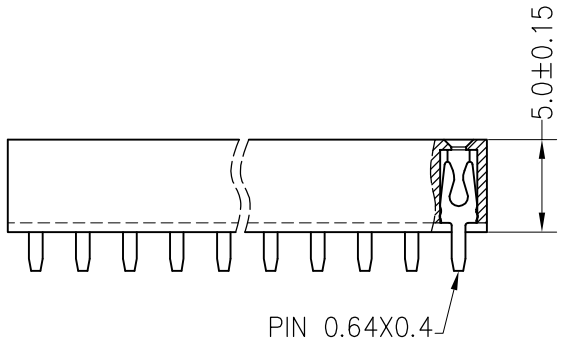


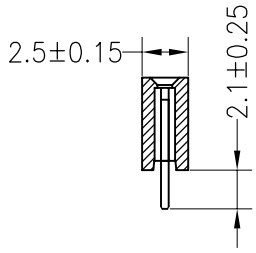


Ordering Information

2250 01 XX X N XX S Y X 02

- No.of Pins Per Row: 1*2~1*40
- Insulator Material Option: A=BK−PBT; B=BK−PA66; C=BK−PA6T; D=BK−PA46; E=BK−PA9T; F=BK−LCP
- Contact Plating: G0:Gold Flash; G1:3U" Gold; G2:5U" Gold; G3:10U" Gold; G4:15U" Gold; G5:30U" Gold; S0:Gold Flash/Tin; SN:Tin
- Packing: 0=PE Bag; T=Tube





REV	DATE	MODIFICATION DESCRIPTION	CHANGE
A0	2012.03.28	NEW DRAWING	

OPERATION		DRAW	Liu Miao		SCALE	FIT
X.X	±0.30				UNIT	mm
X.XX	±0.20	CHECK			SIZE	A4
X.XXX	±0.10				SHEET	1/1
Angle	±3°	APPROVE			PROJ.	
DIM	TOL					

WFD 深圳市旺富达电子有限公司
CONN SHEN ZHEN WFD ELECTRONICS CO., LTD

PART NO.	225001XXXNXXSYX02
TITLE:	2.54PF H5.0mm 1xNpin 180° DIP